



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/809,182 Confirmation No. 6820
Applicant(s) : UMENO, Kuniharu et al.
Filed : 03/25/2004
TC/A.U. : 1712
Examiner : To Be Assigned
Title : Resin Composition for Encapsulating Semiconductor Chip and
Semiconductor Device Therewith

Docket No. : 033036.076
Customer No. : 25461

Mail Stop MISSING PARTS
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INFORMATION DISCLOSURE STATEMENT

Pursuant to the duty of disclosure under 37 C.F.R. 1.56, Applicants are enclosing an Information Disclosure Statement by Applicant (Form PTO/SB/08a) and copies of the patent documents cited therein. The relevance of the cited documents is indicated in the patent specification filed on March 25, 2004.

It is respectfully requested that the cited documents be considered by the Examiner in the above-identified patent application and that the cited documents be made officially of record therein. It is further requested that a listing of the same appear on the face of any patent which may issue from this application.

A first Official Action has not yet issued for this application. Therefore, it is believed that no fees are due under 37 C.F.R. Section 1.97(b)(3).

Respectfully submitted,

By: Robert G. Weilacher, Reg. No. 20,531

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